SOT1934-1
HLLGA17R, thermal enhanced low profile land grid array package, 17 terminals, 0.65 mm pitch, 4 mm x 3 mm x 1.348 mm body
27 June 2019

1 Package summary

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2 Package outline

Figure 1. Package outline HLLGA17R (SOT1934-1)
Figure 2. Package outline detail HLLGA17R (SOT1934-1)
3 Soldering

Figure 3. Reflow soldering footprint part1 for HLLGA17R (SOT1934-1)
PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

This sheet serves only as a guideline to help develop a user specific solution. Development effort will still be required by end users to optimize PCB mounting processes and board design in order to meet individual/specific requirements.

Figure 4. Reflow soldering footprint part2 for HLLGA17R (SOT1934-1)
Figure 5. Reflow soldering footprint part3 for HLLGA17R (SOT1934-1)

RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.
NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.

Figure 6. Package outline note HLLGA17R (SOT1934-1)
4  Legal information

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